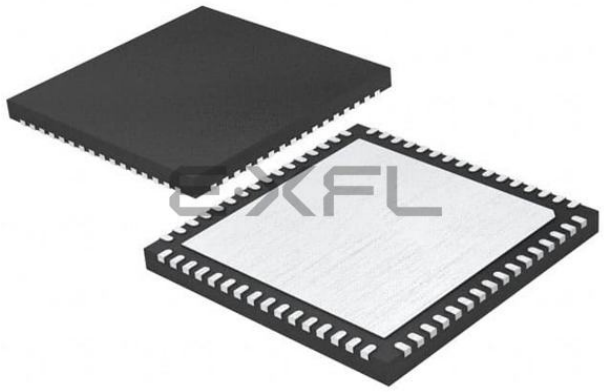
Microchip Technology - PIC32MX320F128HT-80V/MR Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx320f128ht-80v-mr

PIC32MX3XX/4XX

High-Performance, General Purpose and USB 32-bit Flash Microcontrollers

High-Performance 32-bit RISC CPU:

- MIPS32® M4K® 32-bit core with 5-stage pipeline
- 80 MHz maximum frequency
- 1.56 DMIPS/MHz (Dhrystone 2.1) performance at 0 wait state Flash access
- Single-cycle multiply and high-performance divide unit
- MIPS16e® mode for up to 40% smaller code size
- Two sets of 32 core register files (32-bit) to reduce interrupt latency
- Prefetch Cache module to speed execution from Flash

Microcontroller Features:

- Operating temperature range of -40ºC to +105ºC
- Operating voltage range of 2.3V to 3.6V
- 32K to 512K Flash memory (plus an additional 12 KB of boot Flash)
- 8K to 32K SRAM memory
- Pin-compatible with most PIC24/dsPIC® DSC devices
- Multiple power management modes
- Multiple interrupt vectors with individually programmable priority
- Fail-Safe Clock Monitor Mode
- Configurable Watchdog Timer with on-chip Low-Power RC Oscillator for reliable operation

Peripheral Features:

- Atomic SET, CLEAR and INVERT operation on select peripheral registers
- Up to 4-channel hardware DMA with automatic data size detection
- USB 2.0-compliant full-speed device and On-The-Go (OTG) controller
- USB has a dedicated DMA channel
- 3 MHz to 25 MHz crystal oscillator
- Internal 8 MHz and 32 kHz oscillators
- Separate PLLs for CPU and USB clocks
- Two I^2C™ modules
- Two UART modules with:
  - RS-232, RS-485 and LIN support
  - IrDA® with on-chip hardware encoder and decoder
- Up to two SPI modules
- Parallel Master and Slave Port (PMP/PSP) with 8-bit and 16-bit data and up to 16 address lines
- Hardware Real-Time Clock and Calendar (RTCC)
- Five 16-bit Timers/Counters (two 16-bit pairs combine to create two 32-bit timers)
- Five capture inputs
- Five compare/PWM outputs
- Five external interrupt pins
- High-Speed I/O pins capable of toggling at up to 80 MHz
- High-current sink/source (18 mA/18 mA) on all I/O pins
- Configurable open-drain output on digital I/O pins

Debug Features:

- Two programming and debugging Interfaces:
  - 2-wire interface with unintrusive access and real-time data exchange with application
  - 4-wire MIPS® standard enhanced JTAG interface
- Unintrusive hardware-based instruction trace
- IEEE Standard 1149.2-compatible (JTAG) boundary scan

Analog Features:

- Up to 16-channel 10-bit Analog-to-Digital Converter:
  - 1000 ksps conversion rate
  - Conversion available during Sleep, Idle
- Two Analog Comparators

TABLE 3: PIN NAMES: PIC32MX320F128L, PIC32MX340F128L, PIC32MX360F128L, AND PIC32MX360F512L DEVICES (CONTINUED)

Pin Number	Full Pin Name
K4	AN8/C1OUT/RB8
K5	No Connect (NC)
K6	U2CTS/RF12
K7	AN14/PMALH/PMA1/RB14
K8	VDD
K9	U1RTS/CN21/RD15
K10	U1TX/RF3
K11	U1RX/RF2
L1	PGEC2/AN6/OCFA/RB6
L2	VREF-/CVREF-/PMA7/RA9

Pin Number	Full Pin Name
L3	AVSS
L4	AN9/C2OUT/RB9
L5	AN10/CVREFOUT/PMA13/RB10
L6	U2RTS/RF13
L7	AN13/PMA10/RB13
L8	AN15/OCFB/PMALL/PMA0/CN12/RB15
L9	CN20/U1CTS/RD14
L10	U2RX/PMA9/CN17/RF4
L11	U2TX/PMA8/CN18/RF5

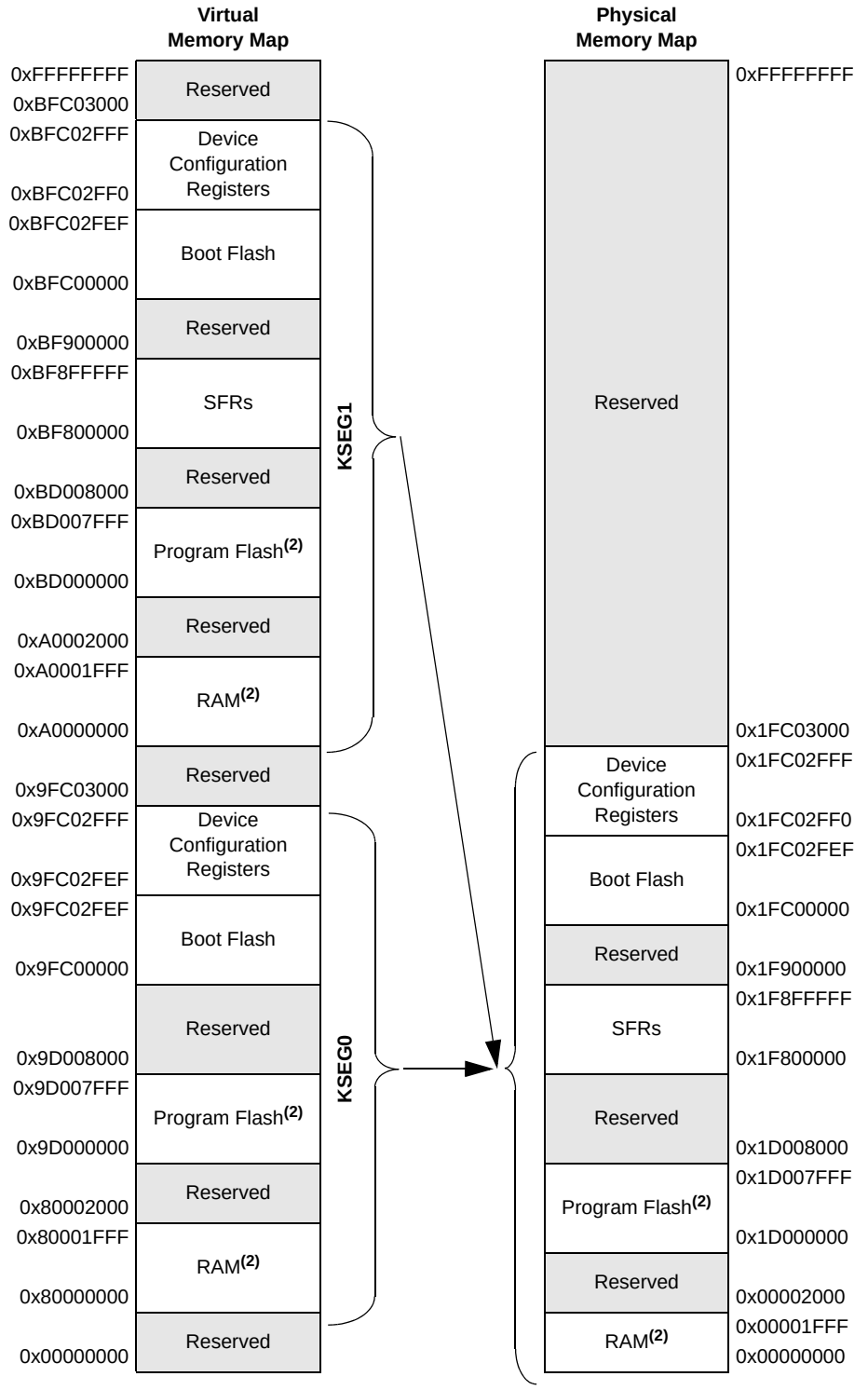
TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
PMD0	60	93	A4	I/O	TTL/ST	Parallel Master Port Data (De-multiplexed Master mode) or Address/Data (Multiplexed Master modes).
PMD1	61	94	B4	I/O	TTL/ST	
PMD2	62	98	B3	I/O	TTL/ST	
PMD3	63	99	A2	I/O	TTL/ST	
PMD4	64	100	A1	I/O	TTL/ST	
PMD5	1	3	D3	I/O	TTL/ST	
PMD6	2	4	C1	I/O	TTL/ST	
PMD7	3	5	D2	I/O	TTL/ST	
PMD8	—	90	A5	I/O	TTL/ST	
PMD9	—	89	E6	I/O	TTL/ST	
PMD10	—	88	A6	I/O	TTL/ST	
PMD11	—	87	B6	I/O	TTL/ST	
PMD12	—	79	A9	I/O	TTL/ST	
PMD13	—	80	D8	I/O	TTL/ST	
PMD14	—	83	D7	I/O	TTL/ST	
PMD15	—	84	C7	I/O	TTL/ST	
PMRD	53	82	B8	O	—	Parallel Master Port Read Strobe.
PMWR	52	81	C8	O	—	Parallel Master Port Write Strobe.
PMALL	30	44	L8	O	—	Parallel Master Port Address Latch Enable low-byte (Multiplexed Master modes).
PMALH	29	43	K7	O	—	Parallel Master Port Address Latch Enable high-byte (Multiplexed Master modes).
VBUS	34	54	H8	I	Analog	USB Bus Power Monitor.
VUSB	35	55	H9	P	—	USB Internal Transceiver Supply. If the USB module is *not* used, this pin must be connected to VDD.
VBUSON	11	20	H1	O	—	USB Host and OTG Bus Power Control Output.
D+	37	57	H10	I/O	Analog	USB D+.
D-	36	56	J11	I/O	Analog	USB D-.
USBID	33	51	K10	I	ST	USB OTG ID Detect.
ENVREG	57	86	A7	I	ST	Enable for On-Chip Voltage Regulator.
TRCLK	—	91	C5	O	—	Trace Clock.
TRD0	—	97	A3	O	—	Trace Data Bits 0-3.
TRD1	—	96	C3	O	—	
TRD2	—	95	C4	O	—	
TRD3	—	92	B5	O	—	
PGED1	16	25	K2	I/O	ST	Data I/O pin for programming/debugging communication channel 1.
PGEC1	15	24	K1	I	ST	Clock input pin for programming/debugging communication channel 1.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

FIGURE 4-1: MEMORY MAP ON RESET FOR PIC32MX320F032H AND PIC32MX420F032H DEVICES(1)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS61115)) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

TABLE 4-8: INPUT CAPTURE1-5 REGISTERS MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2000	IC1CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2010	IC1BUF	31:16	IC1BUF<31:0>																xxxx
		15:0																	xxxx
2200	IC2CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2210	IC2BUF	31:16	IC2BUF<31:0>																xxxx
		15:0																	xxxx
2400	IC3CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2410	IC3BUF	31:16	IC3BUF<31:0>																xxxx
		15:0																	xxxx
2600	IC4CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2610	IC4BUF	31:16	IC4BUF<31:0>																xxxx
		15:0																	xxxx
2800	IC5CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2810	IC5BUF	31:16	IC5BUF<31:0>																xxxx
		15:0																	xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-12: SPI1-2 REGISTERS MAP(1,2)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5800	SPI1CON	31:16	FRMEN	FRMSYNC	FRMPOL	—	—	—	—	—	—	—	—	—	—	—	SPIFE	—	0000
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	—	—	—	—	—	0000
5810	SPI1STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	SPIBUSY	—	—	—	—	SPIROV	—	—	SPITBE	—	—	SPIRBF	0008
5820	SPI1BUF	31:16	DATA<31:0>																0000
		15:0																	0000
5830	SPI1BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	BRG<8:0>									0000
5A00	SPI2CON	31:16	FRMEN	FRMSYNC	FRMPOL	—	—	—	—	—	—	—	—	—	—	—	SPIFE	—	0008
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	—	—	—	—	—	0000
5A10	SPI2STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	SPIBUSY	—	—	—	—	SPIROV	—	—	SPITBE	—	—	SPIRBF	0008
5A20	SPI2BUF	31:16	DATA<31:0>																0000
		15:0																	0000
5A30	SPI2BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	BRG<8:0>									0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table except SPIxBUF have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: SPI2 Module is not present on PIC32MX420FXXXX/440FXXXX devices.

TABLE 4-25: PORTD REGISTERS MAP FOR PIC32MX320F128L, PIC32MX340F128L, PIC32MX360F256L, PIC32MX360F512L, PIC32MX440F128L, PIC32MX460F256L AND PIC32MX460F512L DEVICES ONLY(1)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
60C0	TRISD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TRISD15	TRISD14	TRISD13	TRISD12	TRISD11	TRISD10	TRISD9	TRISD8	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	FFFF
60D0	PORTD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	RD15	RD14	RD13	RD12	RD11	RD10	RD9	RD8	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx
60E0	LATD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	LATD15	LATD14	LATD13	LATD12	LATD11	LATD10	LATD9	LATD8	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	xxxx
60F0	ODCD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ODCD15	ODCD14	ODCD13	ODCD12	ODCD11	ODCD10	ODCD9	ODCD8	ODCD7	ODCD6	ODCD5	ODCD4	ODCD3	ODCD2	ODCD1	ODCD0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-26: PORTD REGISTERS MAP FOR PIC32MX320F032H, PIC32MX320F064H, PIC32MX320F128H, PIC32MX340F128H, PIC32MX340F256H, PIC32MX340F512H, PIC32MX420F032H, PIC32MX440F128H, PIC32MX440F256H AND PIC32MX440F512H DEVICES ONLY(1)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
60C0	TRISD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	TRISD11	TRISD10	TRISD9	TRISD8	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	0FFF
60D0	PORTD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	RD11	RD10	RD9	RD8	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx
60E0	LATD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	LATD11	LATD10	LATD9	LATD8	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	xxxx
60F0	ODCD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	ODCD11	ODCD10	ODCD9	ODCD8	ODCD7	ODCD6	ODCD5	ODCD4	ODCD3	ODCD2	ODCD1	ODCD0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

NOTES:

12.0 I/O PORTS

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 12. "I/O Ports"** (DS61120) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

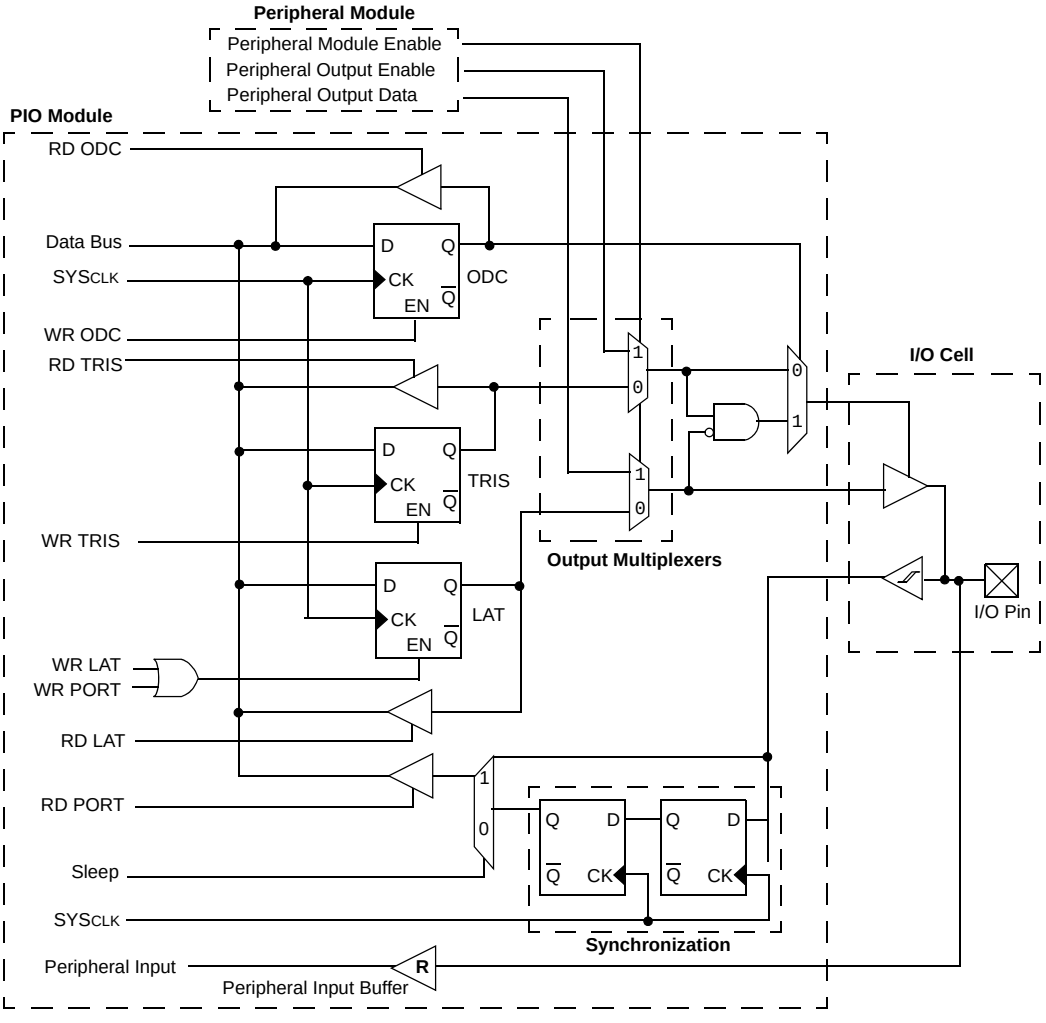
General purpose I/O pins are the simplest of peripherals. They allow the PIC® MCU to monitor and control other devices. To add flexibility and functionality, some pins are multiplexed with alternate function(s). These functions depend on which peripheral features are on the device. In general, when a peripheral is functioning, that pin may not be used as a general purpose I/O pin.

Following are some of the key features of this module:

- Individual Output Pin Open-drain Enable/Disable
- Individual Input Pin Weak Pull-up Enable/Disable
- Monitor Selective Inputs and Generate Interrupt when Change in Pin State is Detected
- Operation during CPU Sleep and Idle modes
- Fast Bit Manipulation using CLR, SET and INV Registers

Figure 12-1 illustrates a block diagram of a typical multiplexed I/O port.

FIGURE 12-1: BLOCK DIAGRAM OF A TYPICAL MULTIPLEXED PORT STRUCTURE



Legend: R = Peripheral input buffer types may vary. Refer to Table 1-1 for peripheral details.

Note: This block diagram is a general representation of a shared port/peripheral structure for illustration purposes only. The actual structure for any specific port/peripheral combination may be different than it is shown here.

15.0 INPUT CAPTURE

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 15. "Input Capture"** (DS61122) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Input Capture module is useful in applications requiring frequency (period) and pulse measurement. The PIC32MX3XX/4XX devices support up to five input capture channels.

The Input Capture module captures the 16-bit or 32-bit value of the selected Time Base registers when an event occurs at the ICx pin. The events that cause a capture event are listed below in three categories:

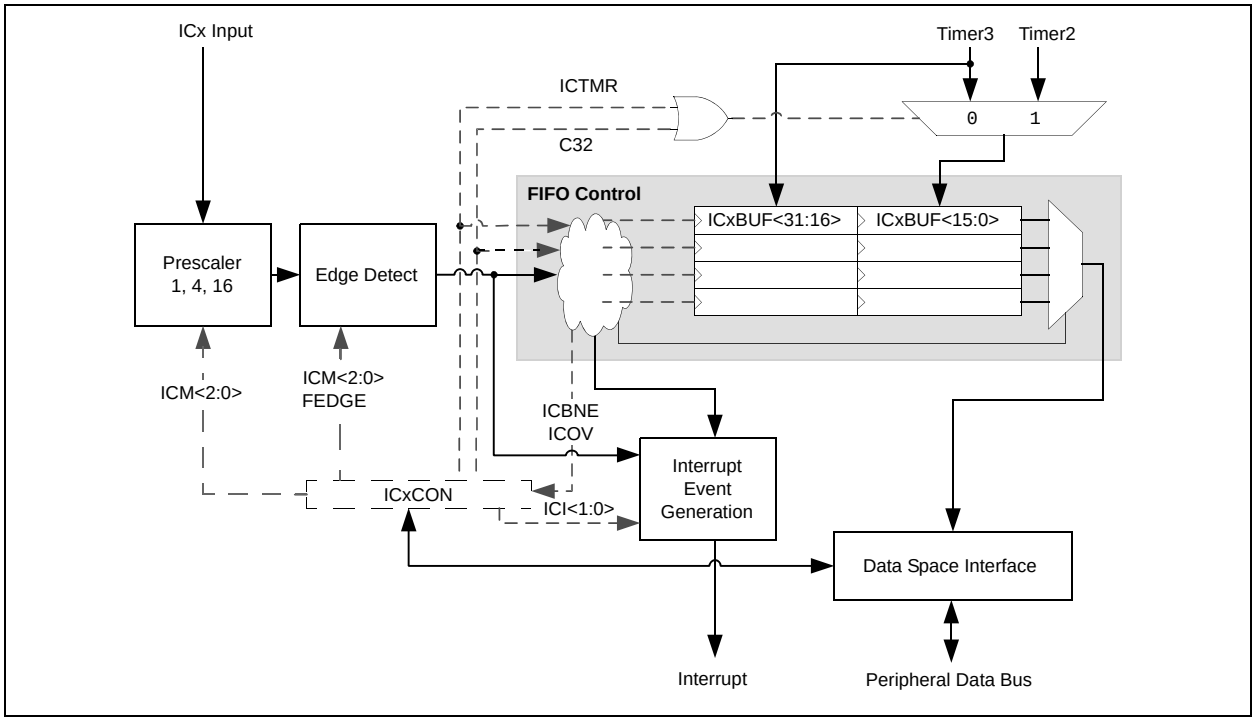
1. Simple Capture Event modes
   - Capture timer value on every falling edge of input at ICx pin
   - Capture timer value on every rising edge of input at ICx pin
2. Capture timer value on every edge (rising and falling)
3. Capture timer value on every edge (rising and falling), specified edge first.
4. Prescaler Capture Event modes
   - Capture timer value on every 4th rising edge of input at ICx pin
   - Capture timer value on every 16th rising edge of input at ICx pin

Each input capture channel can select between one of two 16-bit timers (Timer2 or Timer3) for the time base, or two 16-bit timers (Timer2 and Timer3) together to form a 32-bit timer. The selected timer can use either an internal or external clock.

Other operational features include:

- Device wake-up from capture pin during CPU Sleep and Idle modes
- Interrupt on input capture event
- 4-word FIFO buffer for capture values
  - Interrupt optionally generated after 1, 2, 3 or 4 buffer locations are filled
- Input capture can also be used to provide additional sources of external interrupts

FIGURE 15-1: INPUT CAPTURE BLOCK DIAGRAM



NOTES:

17.0 SERIAL PERIPHERAL INTERFACE (SPI)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 23. "Serial Peripheral Interface (SPI)"** (DS61106) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

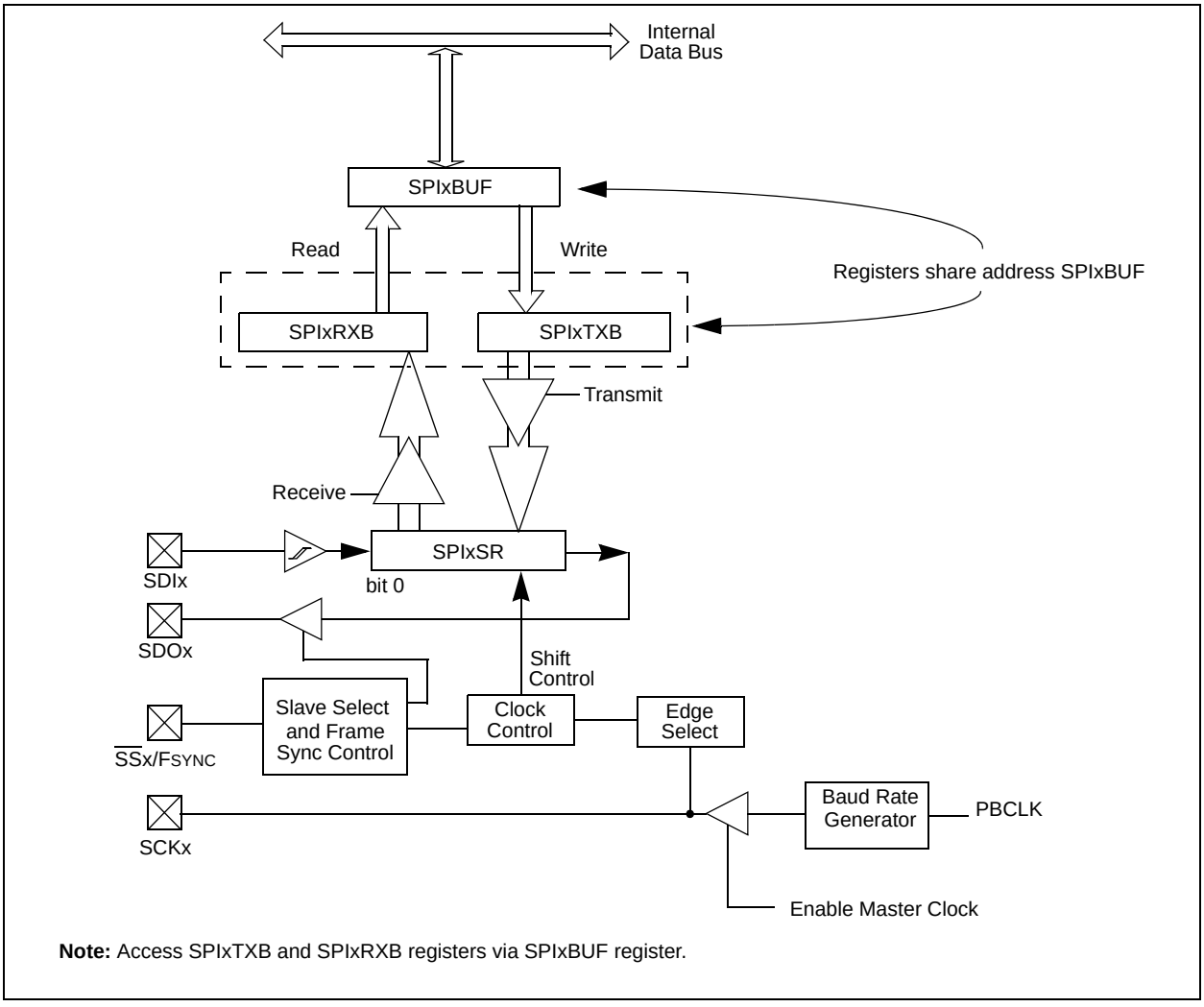
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The SPI module is a synchronous serial interface useful for communicating with external peripherals and other microcontroller devices. These peripheral devices may be Serial EEPROMs, shift registers, display drivers, Analog-to-Digital Converters, etc. The PIC32MX SPI module is compatible with Motorola® SPI and SIOP interfaces.

Following are some of the key features of this module:

- Master and Slave Modes Support
- Four Different Clock Formats
- Framed SPI Protocol Support
- User Configurable 8-bit, 16-bit and 32-bit Data Width
- Separate SPI Data Registers for Receive and Transmit
- Programmable Interrupt Event on every 8-bit, 16-bit and 32-bit Data Transfer
- Operation during CPU Sleep and Idle Mode
- Fast Bit Manipulation using CLR, SET and INV Registers

FIGURE 17-1: SPI MODULE BLOCK DIAGRAM



Note: Access SPIxTXB and SPIxRXB registers via SPIxBUF register.

24.0 COMPARATOR VOLTAGE REFERENCE (CVREF)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. Refer to **Section 20. "Comparator Voltage Reference (CVREF)"** (DS61109) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

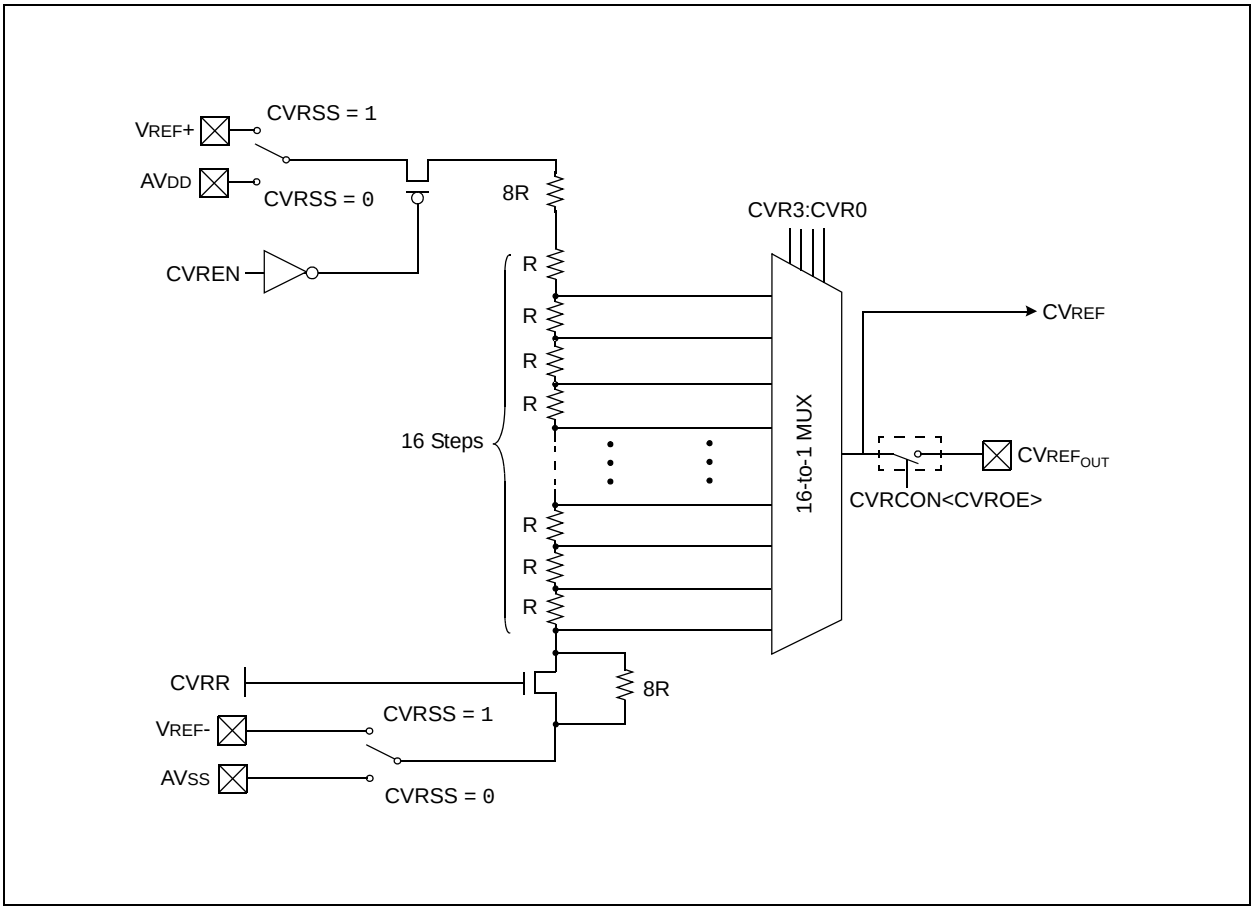
The CVREF is a 16-tap, resistor ladder network that provides a selectable reference voltage. Although its primary purpose is to provide a reference for the analog comparators, it also may be used independently of them.

A block diagram of the module is illustrated in Figure 24-1. The resistor ladder is segmented to provide two ranges of voltage reference values and has a power-down function to conserve power when the reference is not being used. The module's supply reference can be provided from either device VDD/VSS or an external voltage reference. The CVREF output is available for the comparators and typically available for pin output.

The comparator voltage reference has the following features:

- High and low range selection
- Sixteen output levels available for each range
- Internally connected to comparators to conserve device pins
- Output can be connected to a pin

FIGURE 24-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



28.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers and dsPIC® digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB C Compiler for Various Device Families
  - HI-TECH C for Various Device Families
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
  - MPLAB ICD 3
  - PICkit™ 3 Debug Express
- Device Programmers
  - PICkit™ 2 Programmer
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

28.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

- A single graphical interface to all debugging tools
  - Simulator
  - Programmer (sold separately)
  - In-Circuit Emulator (sold separately)
  - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- Debug using:
  - Source files (C or assembly)
  - Mixed C and assembly
  - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

TABLE 29-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD}) (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp			
Parameter No.	**Typical(2)**	**Max.**	**Units**	**Conditions**		
Module Differential Current (Continued)						
DC43	—	1100	µA	-40°C	2.5V	ADC: ΔI_{ADC} **(Notes 3, 4, 6)**
DC43a	—	1100	µA	+25°C		
DC43b	—	1000	µA	+85°C		
DC43h	—	1200	µA	+105ºC		
DC43c	880	—	µA	—	—	ADC: ΔI_{ADC} **(Notes 3, 4)**
DC43e	—	1100	µA	-40°C	3.6V	ADC: ΔI_{ADC} **(Notes 3, 4)**
DC43f	—	1100	µA	+25°C		
DC43g	—	1000	µA	+85°C		
DC43i	—	1200	µA	+105ºC		

Note 1: Base I_{PD} is measured with all digital peripheral modules disabled. All I/Os are configured as inputs and pulled low. WDT and FSCM are disabled.

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: Data is characterized at +70°C and not tested. Parameter is for design guidance only.

6: This parameter is characterized, but not tested in manufacturing.

TABLE 29-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		I/O pins:					
		with TTL Buffer	VSS	—	0.15 VDD	V	**(Note 4)**
		with Schmitt Trigger Buffer	VSS	—	0.2 VDD	V	**(Note 4)**
DI15		$\overline{MCLR}$	VSS	—	0.2 VDD	V	**(Note 4)**
DI16		OSC1 (XT mode)	VSS	—	0.2 VDD	V	**(Note 4)**
DI17		OSC1 (HS mode)	VSS	—	0.2 VDD	V	**(Note 4)**
DI18		SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled **(Note 4)**
DI19		SDAx, SCLx	VSS	—	0.8	V	SMBus enabled **(Note 4)**
	VIH	**Input High Voltage**					
DI20		I/O pins:					
		with Analog Functions	0.8 VDD	—	VDD	V	**(Note 4)**
		Digital Only	0.8 VDD	—		V	**(Note 4)**
		with TTL Buffer	0.25VDD + 0.8V	—	5.5	V	**(Note 4)**
		with Schmitt Trigger Buffer	0.8 VDD	—	5.5	V	**(Note 4)**
DI25		$\overline{MCLR}$	0.8 VDD	—	VDD	V	**(Note 4)**
DI26		OSC1 (XT mode)	0.7 VDD	—	VDD	V	**(Note 4)**
DI27		OSC1 (HS mode)	0.7 VDD	—	VDD	V	**(Note 4)**
DI28		SDAx, SCLx	0.7 VDD	—	5.5	V	SMBus disabled **(Note 4)**
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled, 2.3V ≤VPIN ≤5.5 **(Note 4)**
DI30	ICNPU	**CNxx Pull up Current**	50	250	400	µA	VDD = 3.3V, VPIN = VSS
	IIL	**Input Leakage Current**					**(Note 3)**
DI50		I/O Ports	—	—	±1	µA	VSS ≤VPIN ≤VDD, Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	µA	VSS ≤VPIN ≤VDD, Pin at high-impedance
DI55		$\overline{MCLR}$	—	—	±1	µA	VSS ≤VPIN ≤VDD
DI56		OSC1	—	—	±1	µA	VSS ≤VPIN ≤VDD, XT and HS modes

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

TABLE 29-17: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
OS10	FOSC	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50(3) 50(5)	MHz MHz	EC **(Note 5)** ECPLL **(Note 4)**
OS11		Oscillator Crystal Frequency	3	—	10	MHz	XT **(Note 5)**
OS12			4	—	10	MHz	XTPLL **(Notes 4, 5)**
OS13			10	—	25	MHz	HS **(Note 5)**
OS14			10	—	25	MHz	HSPLL **(Notes 4, 5)**
OS15			32	32.768	100	kHz	SOSC **(Note 5)**
OS20	TOSC	TOSC = 1/FOSC = TCY(2)	—	—	—	—	See parameter OS10 for FOSC value
OS30	TOSL, TOSH	External Clock In (OSC1) High or Low Time	0.45 x TOSC	—	—	ns	EC **(Note 5)**
OS31	TOSR, TOSF	External Clock In (OSC1) Rise or Fall Time	—	—	0.05 x TOSC	ns	EC **(Note 5)**
OS40	TOST	Oscillator Start-up Timer Period (Only applies to HS, HSPLL, XT, XTPLL and SOSC Clock Oscillator modes)	—	1024	—	TOSC	**(Note 5)**
OS41	TFSCM	Primary Clock Fail Safe Time-out Period	—	2	—	ms	**(Note 5)**
OS42	GM	External Oscillator Transconductance	—	12	—	mA/V	VDD = 3.3V TA = +25°C **(Note 5)**

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are characterized but are not tested.

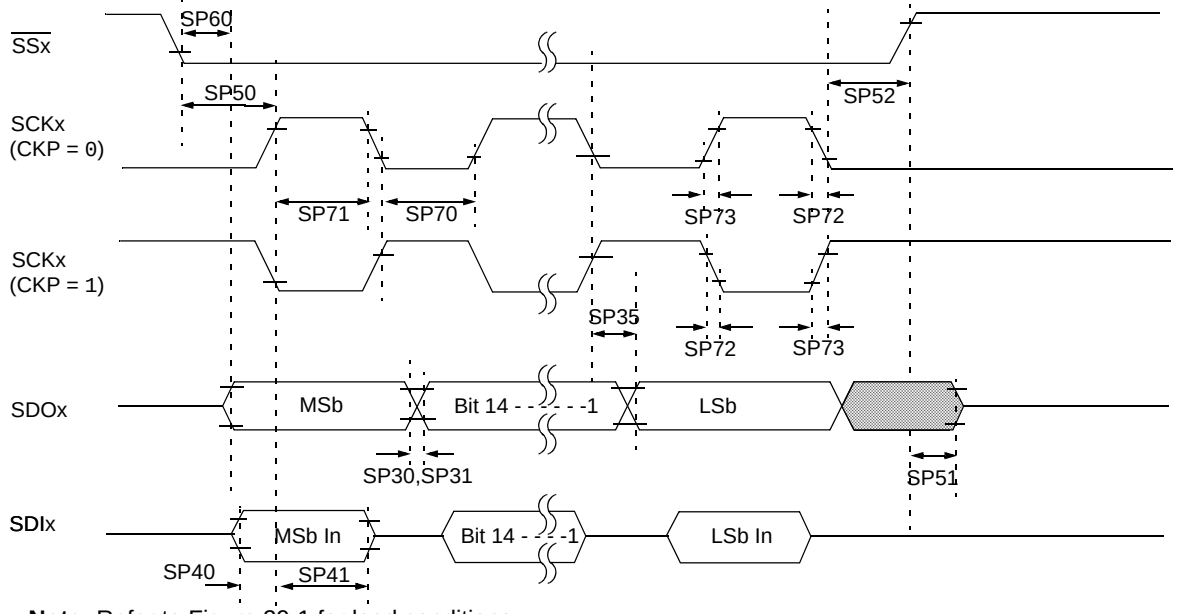
2: Instruction cycle period (TCY) equals the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKI pin.

3: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

4: PLL input requirements: 4 MHz ≤FPLLIN ≤5 MHz (use PLL prescaler to reduce FOSC). This parameter is characterized, but tested at 10 MHz only at manufacturing.

5: This parameter is characterized, but not tested in manufacturing.

FIGURE 29-13: SPIx MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 29-1 for load conditions.

TABLE 29-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V** (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time(3)	Tsck/2	—	—	ns	—
SP71	TscH	SCKx Input High Time(3)	Tsck/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	5	10	ns	—
SP73	TscR	SCKx Input Rise Time	—	5	10	ns	—
SP30	TdoF	SDOx Data Output Fall Time(4)	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time(4)	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	20	ns	VDD > 2.7V
			—	—	30	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓to SCKx ↓or SCKx ↑ Input	175	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance(4)	5	—	25	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge	Tsck + 20	—	—	ns	—
SP60	TssL2doV	$\overline{SDOx}$ Data Output Valid after $\overline{SSx}$ Edge	—	—	25	ns	—

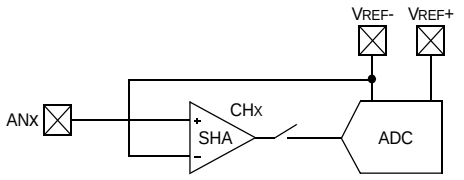
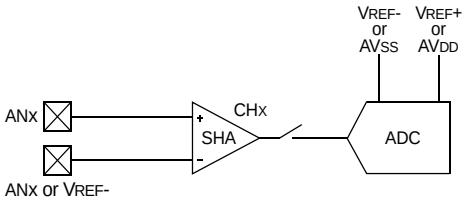
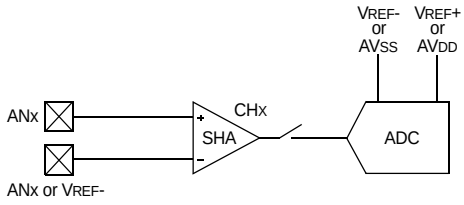
Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

TABLE 29-35: 10-BIT ADC CONVERSION RATE PARAMETERS(2)

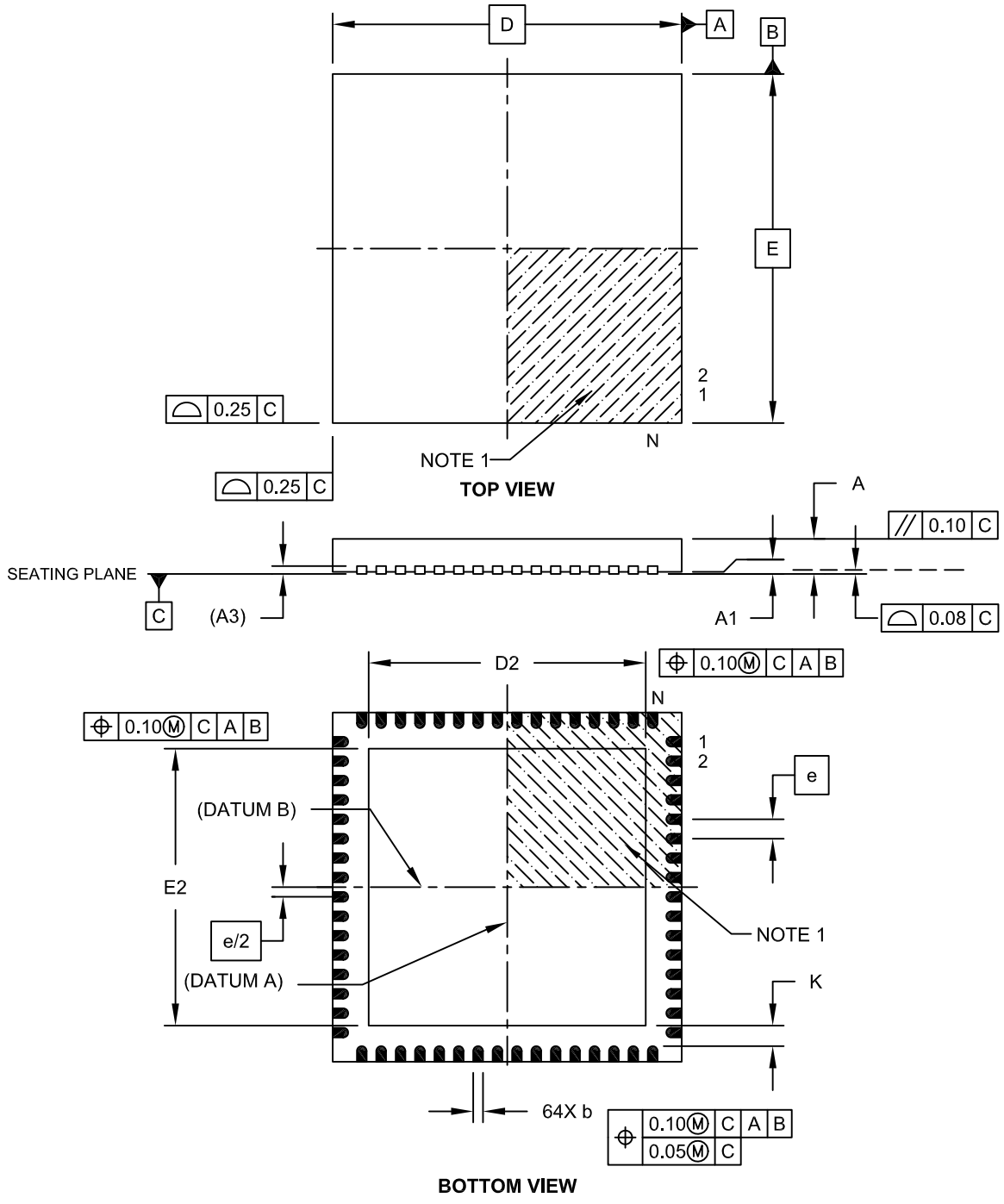
Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp					
ADC Speed	**TAD Minimum**	**Sampling Time Min**	**RS Max**	**VDD**	**ADC Channels Configuration**
1 MIPS to 400 ksps(1)	65 ns	132 ns	500Ω	3.0V to 3.6V	
Up to 400 ksps	200 ns	200 ns	5.0 kΩ	2.5V to 3.6V	
Up to 300 ksps	200 ns	200 ns	5.0 kΩ	2.5V to 3.6V	

Note 1: External VREF- and VREF+ pins must be used for correct operation.

2: These parameters are characterized, but not tested in manufacturing.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN]
With 7.15 x 7.15 Exposed Pad [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-149C Sheet 1 of 2